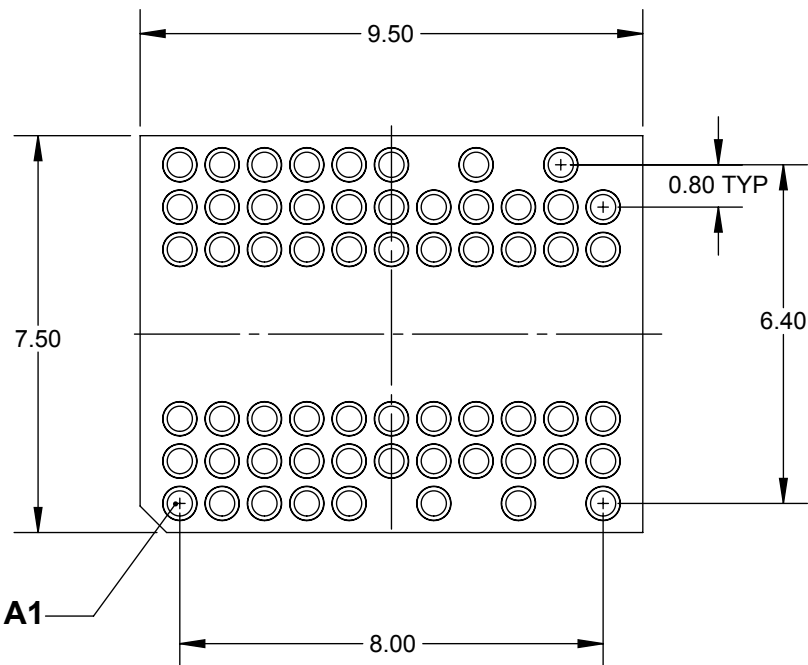
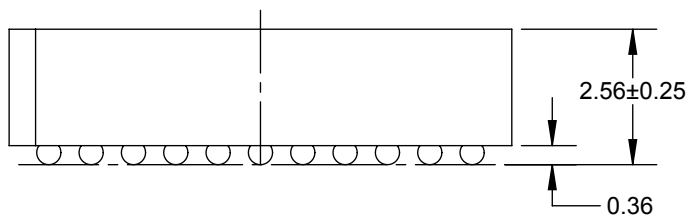


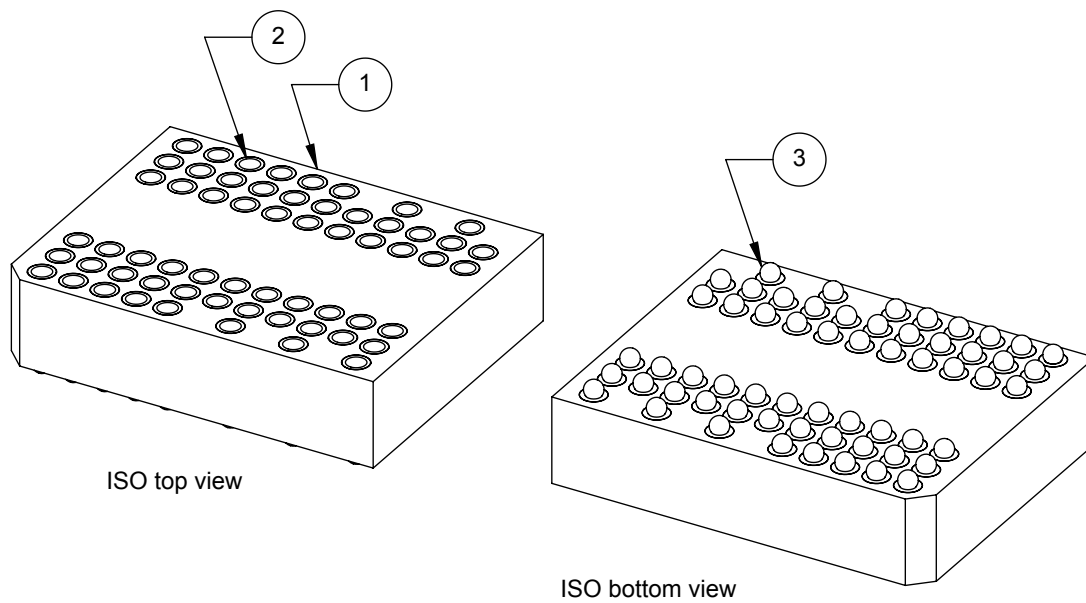
U.S. Patent No. 8,091,222 B2



TOP VIEW



SIDE VIEW



ITEM NO.	DESCRIPTION
1	High Temp Substrate
2	High Density Giga-Snap Receptacle
3	Solder Ball, 0.4572mm dia (See Table)

PART NO. SUFFIX	SOLDER BALL ALLOY
-64	Sn63Pb37
-64F*	Sn96.5Ag3.0Cu0.5
*RoHS Compliant	

Description: Custom Giga-snaP BGA60 SMT Foot

Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: Hole diameters $\pm 0.03\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.025\text{mm}$ [$\pm 0.001"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.13\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA60K-B-64 Drawing SF-BGA60K-B-64-F Drawing	Material: N/A Finish: N/A Weight: N/A	STATUS: Released	SHEET: 1 OF 2	REV. B
		DRAWN BY: M. Raske FILE: SF-BGA060K-B-64	SCALE: 7:1	DATE: 08/15/2012




Ironwood Electronics, Inc.
 Tele: (800) 404-0204
 www.ironwoodelectronics.com

Rev	Date	Initials	Description
A	-	-	Original
B	7/2/15	MT/OA	updated materials to generic definitions

Description:

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters $\pm 0.0254\text{mm}$ [$\pm 0.001"$], Pitches (from true position) $\pm 0.0762\text{mm}$ [$\pm 0.003"$], substrate thickness tolerance $\pm 10\%$, all other tolerances $\pm 0.127\text{mm}$ [$\pm 0.005"$] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com</p>	<p>Material: Finish: Weight:</p>	STATUS: Released	SHEET: 2 OF 2	REV. B
		ENG:	DRAWN BY: M. Raske	SCALE: 7:1
		FILE: SF-BGA060K-B-64	DATE: 08/15/2012	